



VMDSEMI

VUPA003R070NA

Datasheet



VMDSEMI

General Description

Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
30V	7.0mΩ@10V	50A
	11mΩ@4.5V	

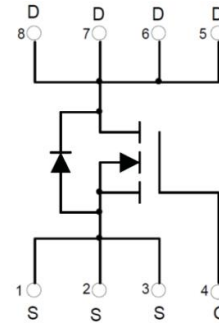
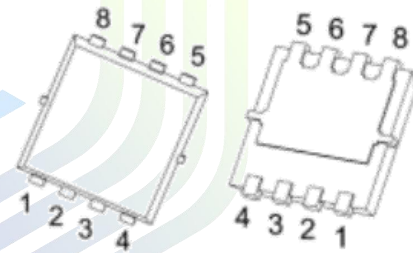


Figure 1 Symbol of VUPA003R070NA

Features

- Trench Technology Power MOSFET
- Low Gate Charge
- Low Gate Resistance
- Low $R_{DS(ON)}$
- 100% UIS Tested

Package Type



PDFN3.3×3.3-8L

Application

- Power Switch
- Battery protection applications

Figure 2 Package Type of VUPA003R070NA

Ordering Information

Product Name	Package
VUPA003R070NA	PDFN3.3X3.3-8L

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current ^{Note1}	I_D	50	A
Pulsed Drain Current ^{Note2}	I_{DM}	200	A
Single Pulsed Avalanche Energy ^{Note3}	E_{AS}	132	mJ
Avalanche Current ^{Note3}	I_{AS}	23	A
Total Power Dissipation ^{Note5}	P_D	25	W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note6}	$R_{\theta JA}$		75		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		5		°C/W



Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=24V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage ^{Note4}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	3.0	V
Static Drain-Source On-Resistance ^{Note4}	$R_{DS(on)}$	$V_{GS}=10V, I_D=10A$		5.5	7.0	mΩ
		$V_{GS}=4.5V, I_D=10A$		7.5	11	
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=15V$		1540		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		207		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		162		pF
Total Gate Charge	Q_g	$V_{DS}=15V$		30		nC
Gate-Source Charge	Q_{gs}	$V_{GS}=10V$		3.7		
Gate-Drain Charge	Q_{gd}	$I_D=10A$		6.6		
Gate Resistance	R_g	$f=1MHz, \text{Open drain}$		2.0		Ω
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=15V$		6.5		ns
Turn-on Rise Time	t_r	$V_{GS}=10V$		2		
Turn-off Delay Time	$t_{d(off)}$	$R_L=0.75\Omega$		17		
Turn-off Fall Time	t_f	$R_{GEN}=3\Omega$		3.5		
Diode Characteristics						
Diode Forward Voltage ^{Note4}	V_{SD}	$V_{GS}=0V, I_S=10A$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD} = 15V, V_{GS} = 10V, L = 0.5mH, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Performance Characteristics

Figure 3: Transfer Characteristics

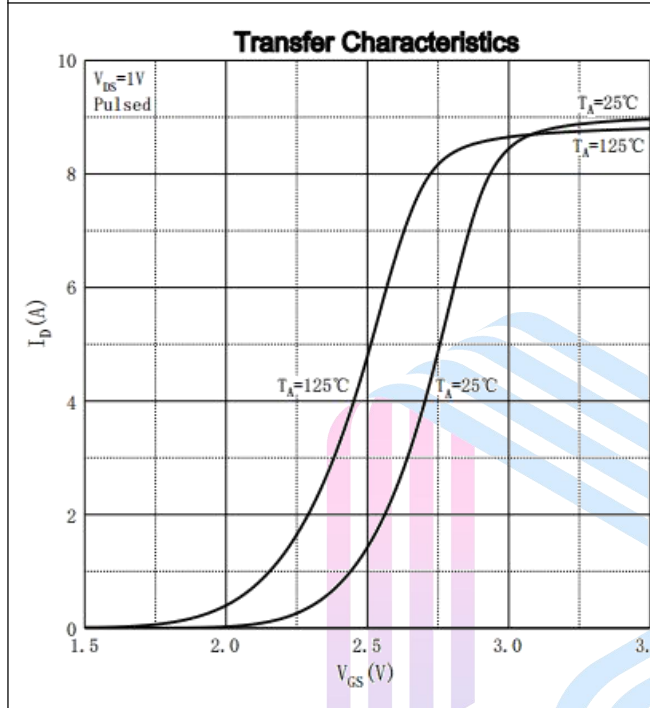


Figure 4: Output Characteristics

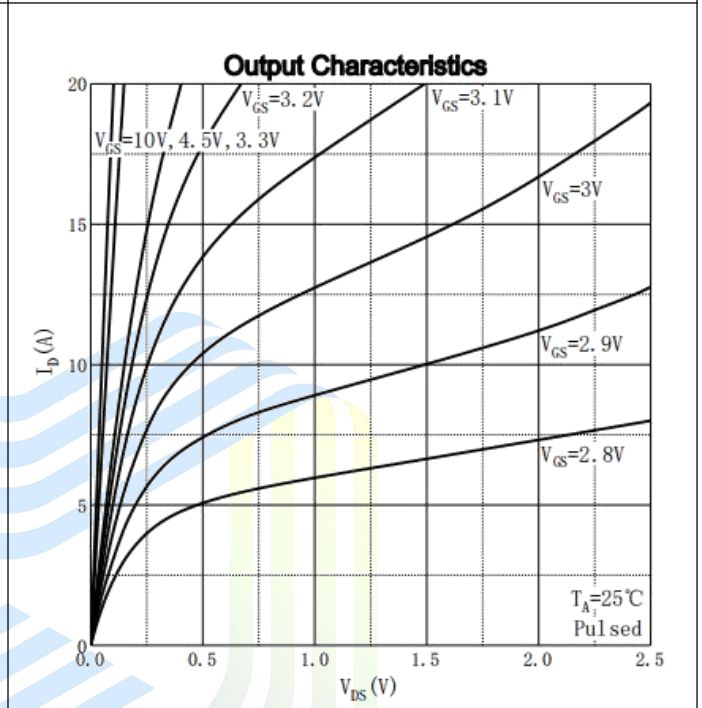


Figure 5: On-Resistance vs. Drain Current

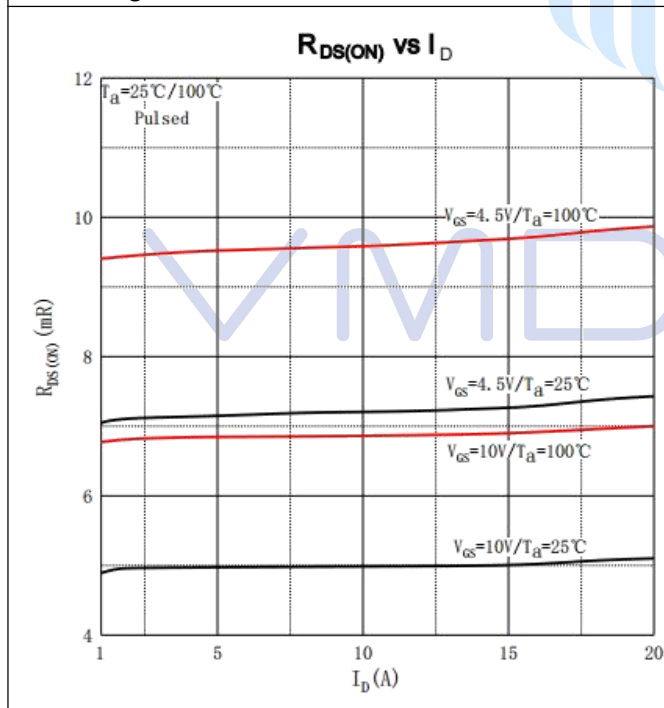


Figure 6: On-Resistance vs. Gate Voltage

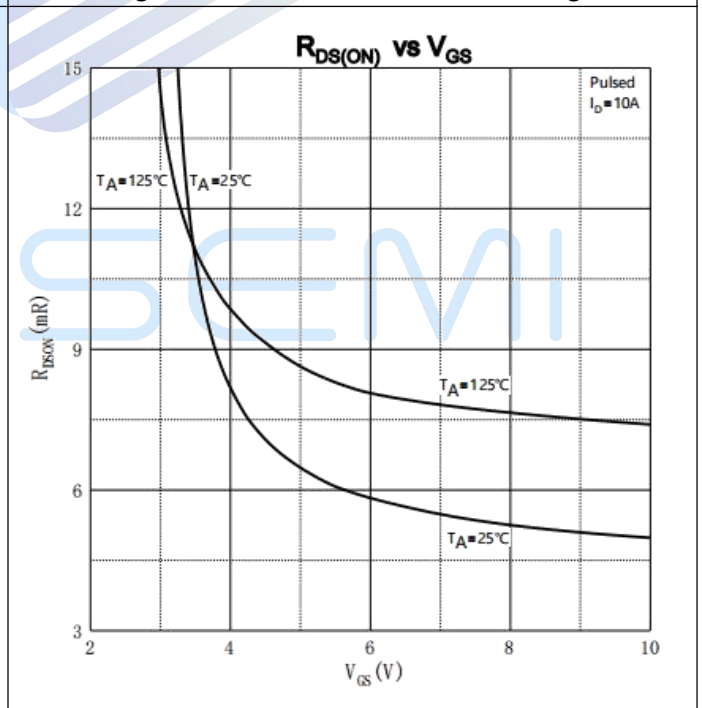


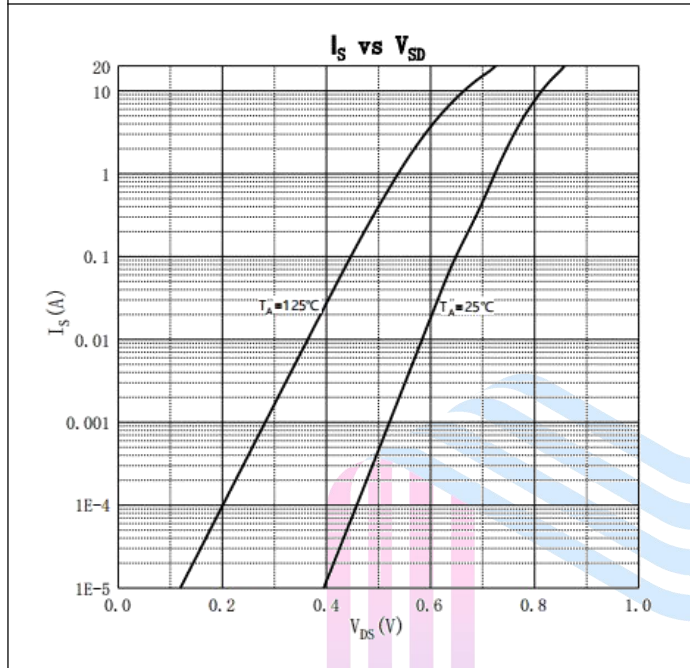
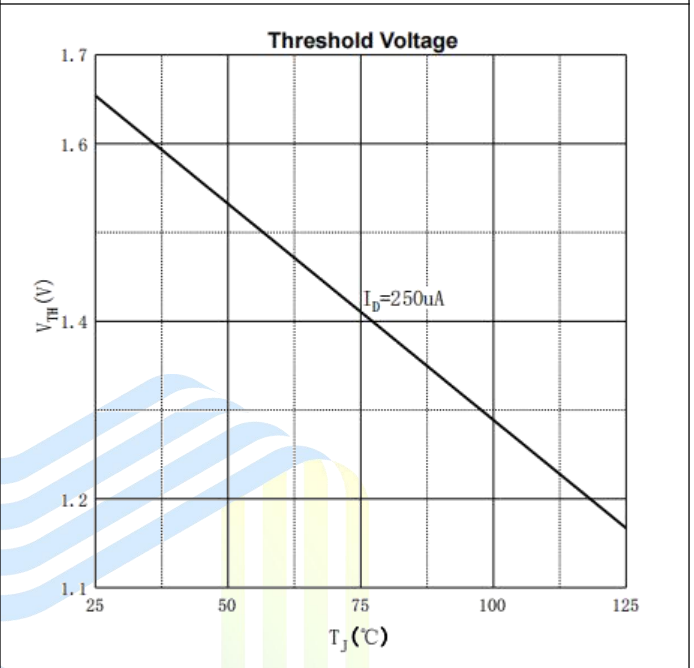
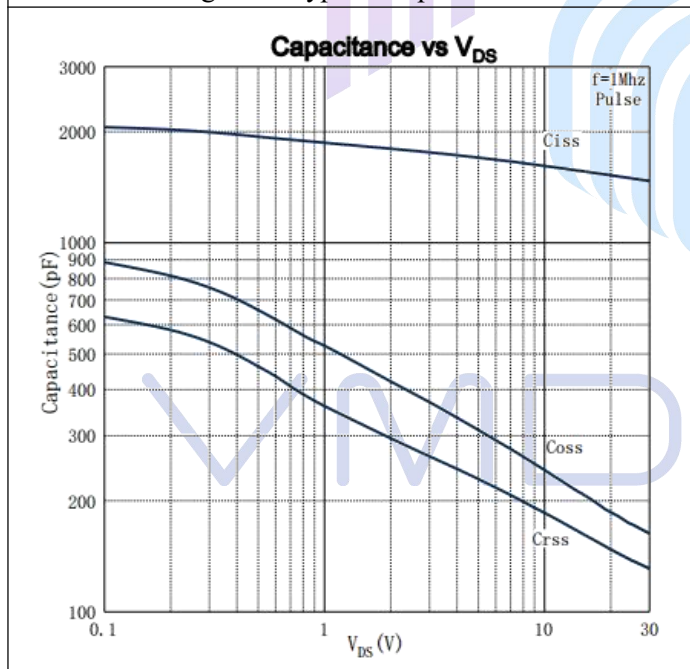
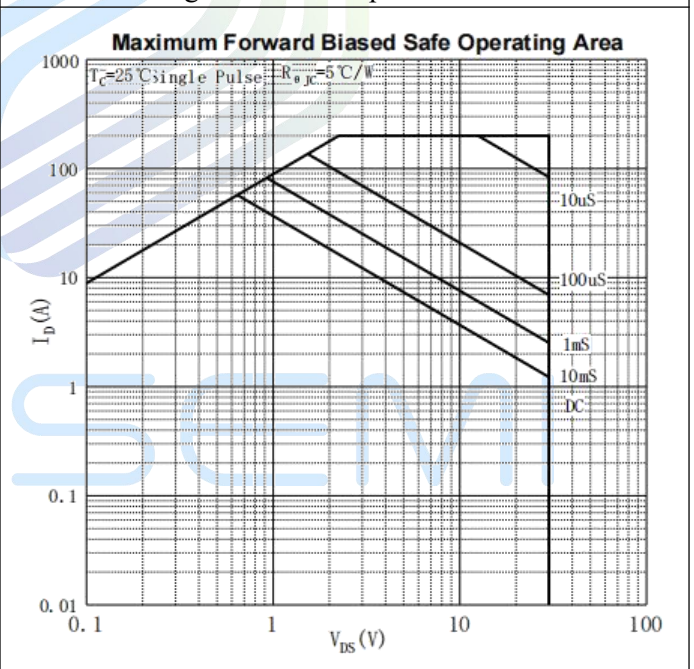
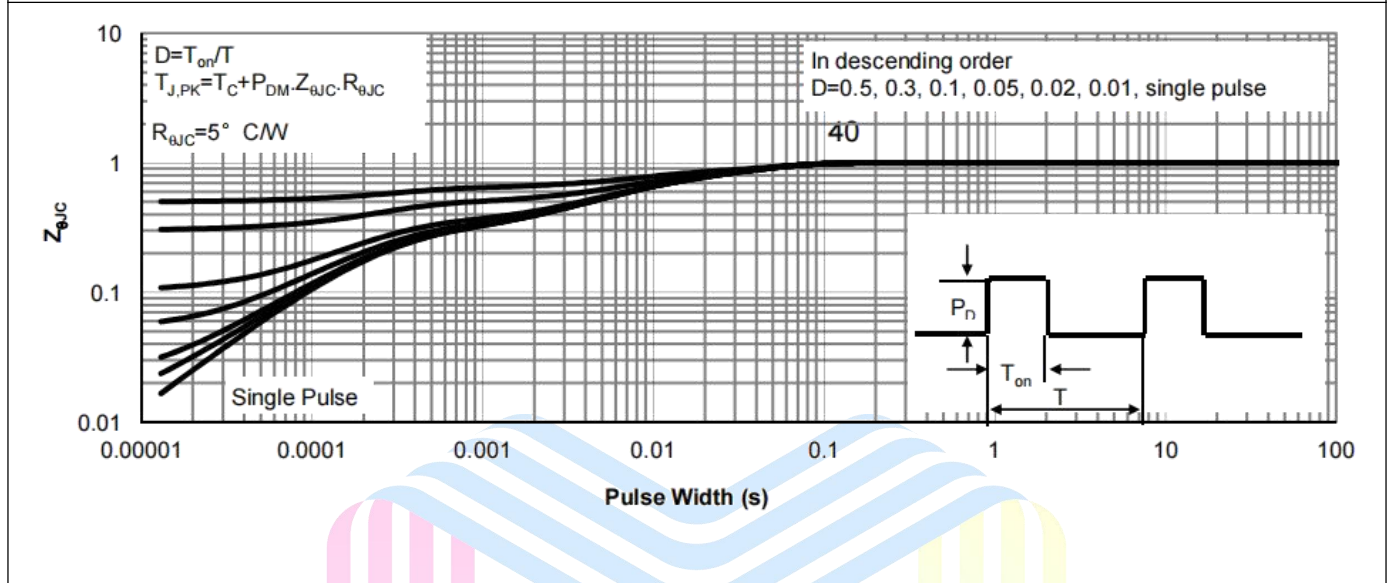
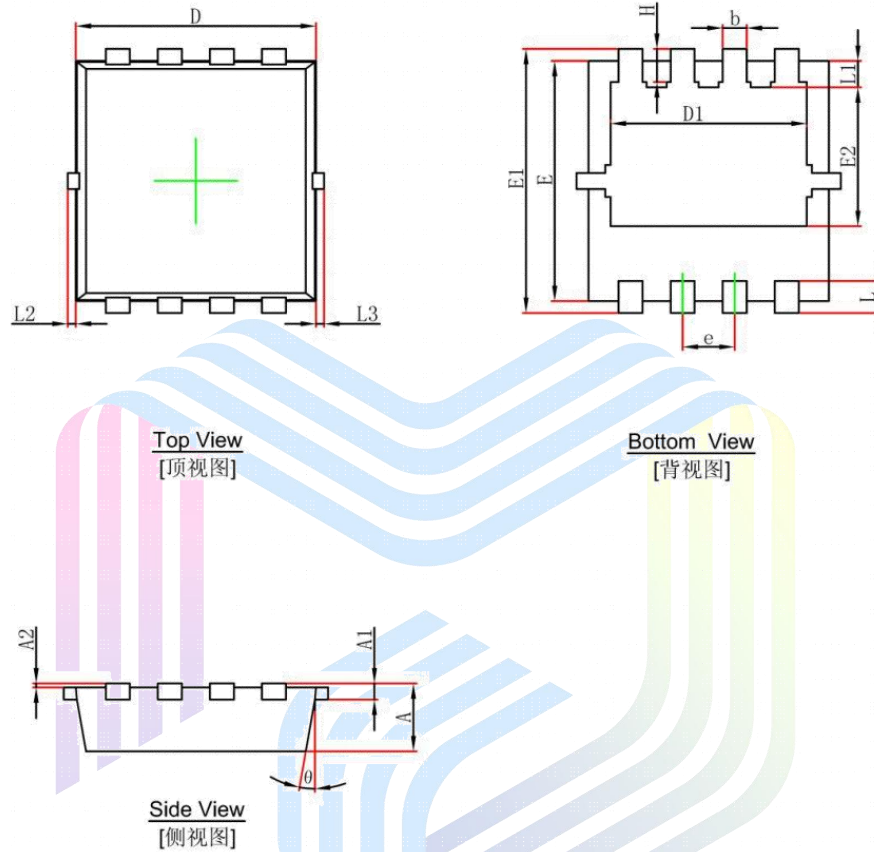
Figure 7: Body Diode Characteristics

Figure 8: Threshold Voltage

Figure 9: Typical Capacitance

Figure 10: Safe Operation Area


Figure 11: Normalized Maximum Transient Thermal Impedance




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Mechanical Dimensions:
PDFN3.3×3.3-8L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.152REF		0.006REF	
A2	0.000	0.050	0.000	0.002
D	2.900	3.200	0.114	0.126
D1	2.300	2.600	0.091	0.102
E	2.900	3.200	0.114	0.126
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0.000	0.100	0.000	0.004
L3	0.000	0.100	0.000	0.004
H	0.315	0.515	0.012	0.020
θ	0°	12°	0°	12°

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